



## Material Content Data Sheet

<b>Sales Product Name</b>		BTS149		<b>Issued</b>		15. October 2014			
<b>MA#</b>		MA000039866							
<b>Package</b>		P-TO220-3-1		<b>Weight*</b>		2012.44 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	13.626	0.68	0.68	6771	6771	
leadframe	non noble metal	iron	7439-89-6	0.816	0.04		406		
	inorganic material	phosphorus	7723-14-0	0.245	0.01		122		
wire	non noble metal	copper	7440-50-8	815.335	40.53	40.58	405147	405675	
	non noble metal	aluminium	7429-90-5	2.841	0.14	0.14	1412	1412	
encapsulation	organic material	carbon black	1333-86-4	6.294	0.31		3128		
	inorganic material	antimonytrioxide	1309-64-4	13.161	0.65		6540		
	plastics	brominated resin	-	14.877	0.74		7393		
	plastics	epoxy resin	-	108.719	5.40		54023		
leadfinish	inorganic material	silicondioxide	60676-86-0	429.155	21.32	28.42	213250	284334	
	non noble metal	lead	7439-92-1	2.704	0.13		1344		
	non noble metal	tin	7440-31-5	6.868	0.34	0.47	3413	4757	
plating	non noble metal	nickel	7440-02-0	1.764	0.09	0.09	876	876	
glue	plastics	Polyimide	26023-21-2	0.157	0.01	0.01	78	78	
	solder	non noble metal	antimony	7440-36-0	0.565	0.03		281	
		noble metal	silver	7440-22-4	1.412	0.07		701	
heatspreader	non noble metal	tin	7440-31-5	3.670	0.18	0.28	1824	2806	
	non noble metal	iron	7439-89-6	0.590	0.03		293		
	inorganic material	phosphorus	7723-14-0	0.177	0.01		88		
*deviation	non noble metal	copper	7440-50-8	589.466	29.29	29.33	292910	293291	
	< 10%					Sum in total:	100.00	1000000	

### Important Remarks:

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